

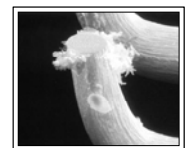
Improve Your Yields Through Innovation

International Test Solutions provides non-destructive cleaning products used by semiconductor manufacturers to remove debris and contaminants generated during wafer level and burn-in/test socket testing. By removing loose debris and adherent contaminants in-line, the quality of the testing data is improved, the test equipment downtime is reduced, throughput is increased and manufacturing yields are improved.

Non-destructive probe card cleaning products for wafer level test applic

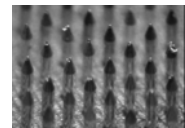
PROBE CLEAN™ Removes Loose Debris From Probe Tips

Probe Clean™ is a unique highly cross-linked polymeric probe card cleaning material that is non-conductive, non-corrosive material that removes and traps the loose debris that accumulates on the probe tips and shaft.



PROBE POLISH™ Non-destructively Maintains High Wafer Yield

Probe Polish™ combines the attractive forces of **Probe Clean™** with uniformly and spatially distributed abrasive particles for the added benefit of removing embedded contaminants during probe cleaning.



PROBE SCRUB™ Restores Performance and Removes Bonded Debris

Probe Scrub™ is a multilayer probe cleaning medium developed for collecting particulates and debris that accumulate on probes during wafer sort and effectively removing "weld nuggets" from the probe tip contact surface.



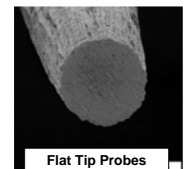
Precision abrasive products for probe card cleaning and probe tip "reforming" and shaping...

PROBE LAP™ Precision Lapping Film

Probe Lap™ is a precision lapping film developed for on-line probe card cleaning to impart a proper contact surface finish with significantly reduced debris generation and provide consistent contaminant removal across a wide temperature range (ambient up to 125°C).

PROBE FORM™ Reshapes Probes for Stable Contact Resistance

Probe Form™ was developed for cantilevered probe technologies to provide a cost effective method of uniformly "reforming" a flat probe tip into a smooth, radius shape.



Non-destructive cleaning products for burn-in/test socket applications...

TEST CELL CONDITIONER (TCC) Collects Loose Debris and Removes Adherent Contaminants From Test Sockets and Contactors

Test Cell Conditioner (TCC) is a unique multilayered "surrogate" package form-factor designed to fit any IC burn-in/test socket and remove all loose debris and embedded oxides from the contacts and test socket.

Represented in the UK and Ireland by, SiSTEM Technology